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(12) **United States Design Patent**
Joniak et al.

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(54) **CONTACT FOR A CONNECTOR**

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(73) Assignee: **Molex, LLC**, Lisle, IL (US)

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Related U.S. Application Data

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(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/154**

(58) **Field of Classification Search**
USPC D13/154, 133, 146
CPC H01H 1/385; H01H 1/62
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a contact for a connector, as shown and described.

DESCRIPTION

FIG. **1** is a front perspective view of a contact for a connector showing our new design;
FIG. **2** is a front view thereof;
FIG. **3** is a rear view thereof;
FIG. **4** is a right side view thereof;
FIG. **5** is a left side view thereof;
FIG. **6** is a top view thereof; and,
FIG. **7** is a bottom view thereof.
The grey-fill shading is used as an aid to represent surface contour.

1 Claim, 7 Drawing Sheets

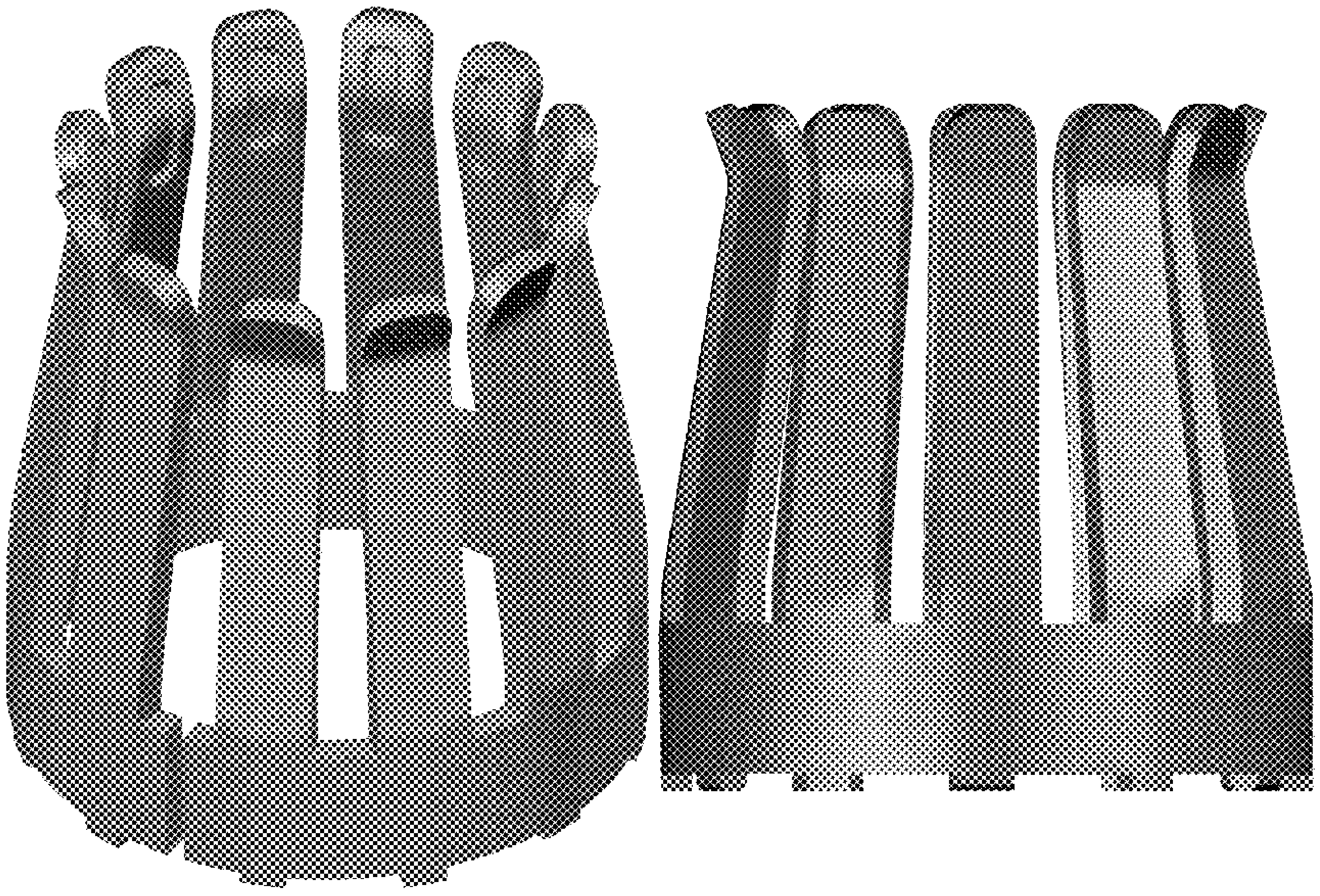

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FIG. 1

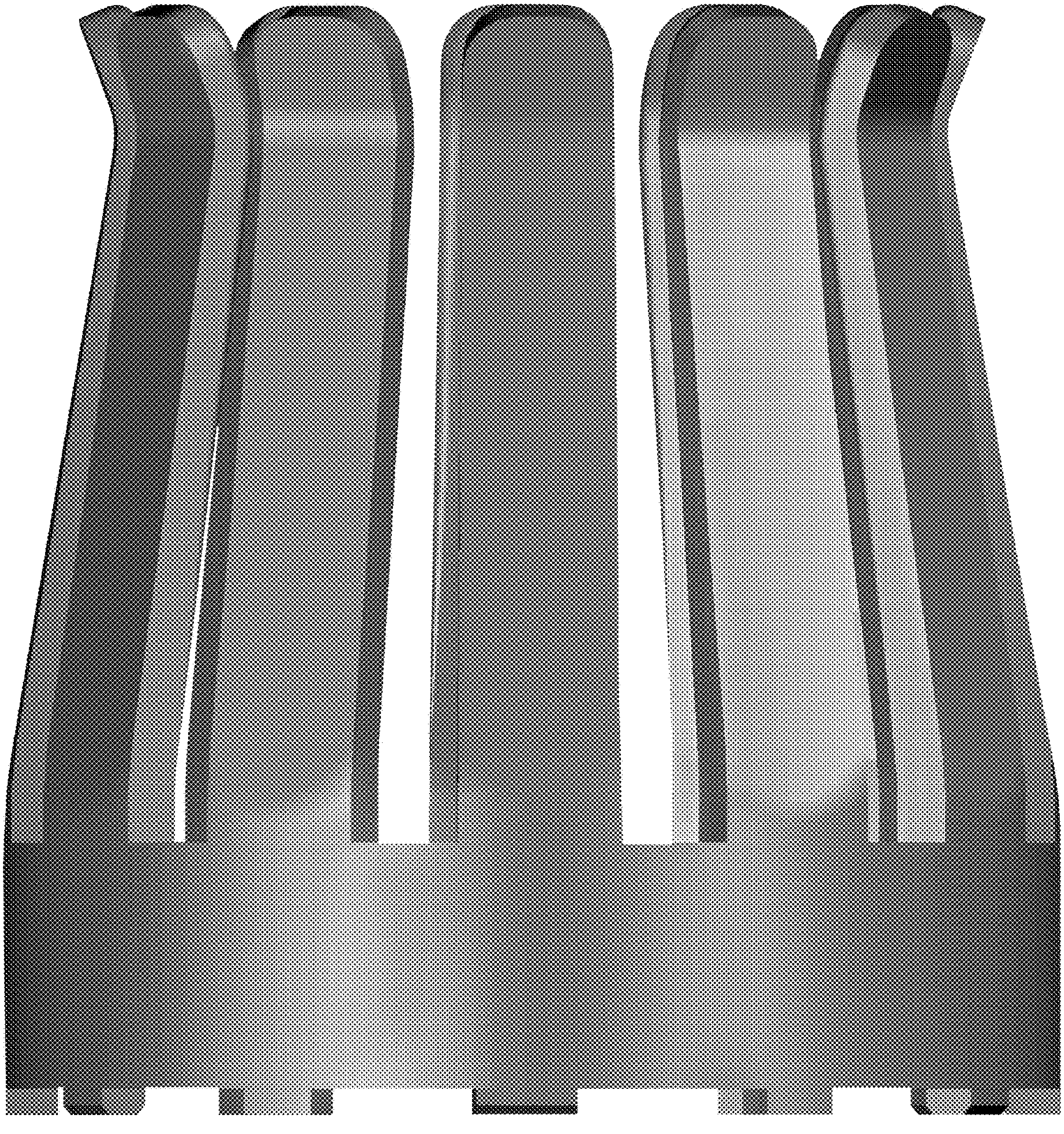

FIG. 2

FIG. 3

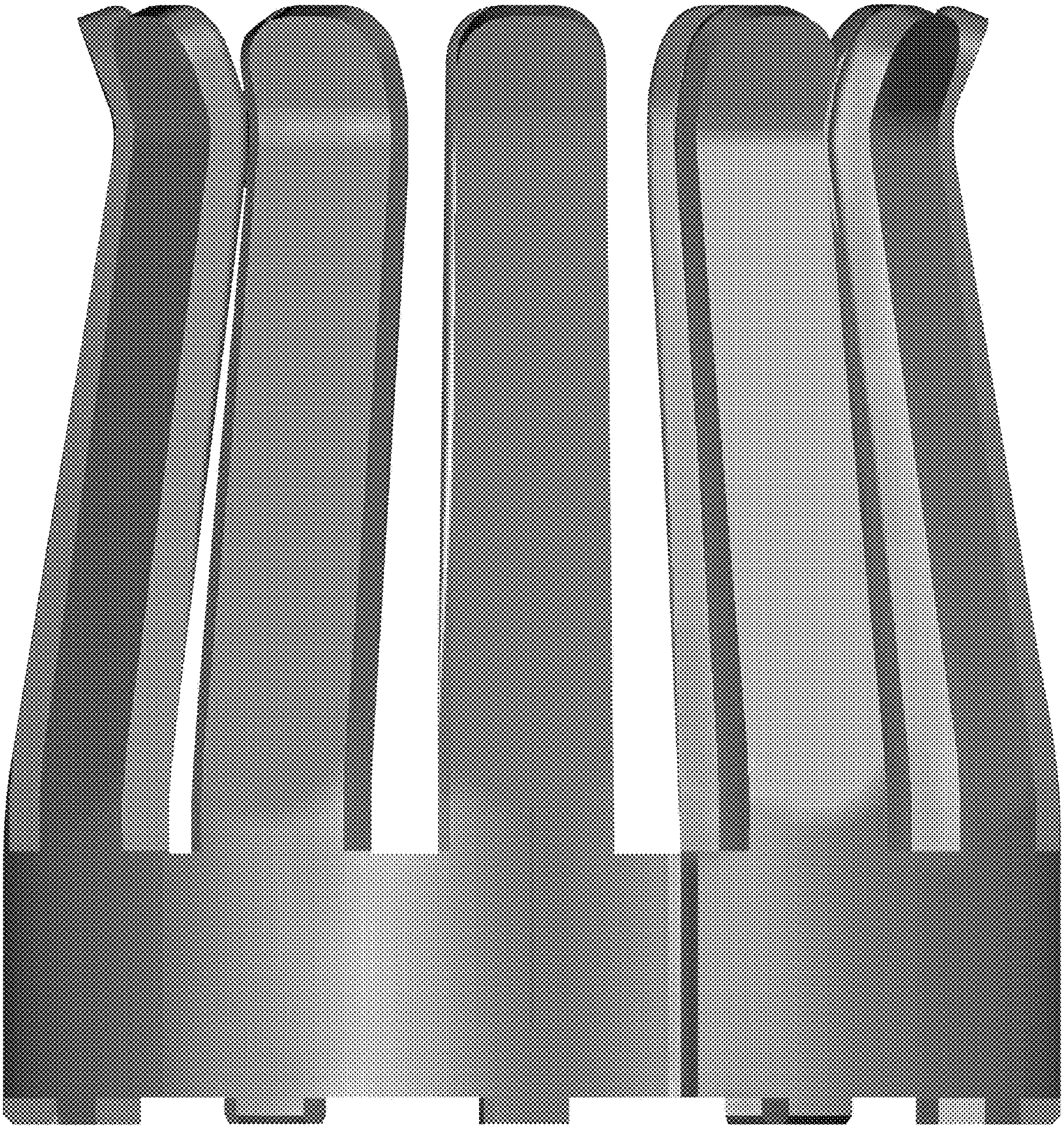

FIG. 4

FIG. 5

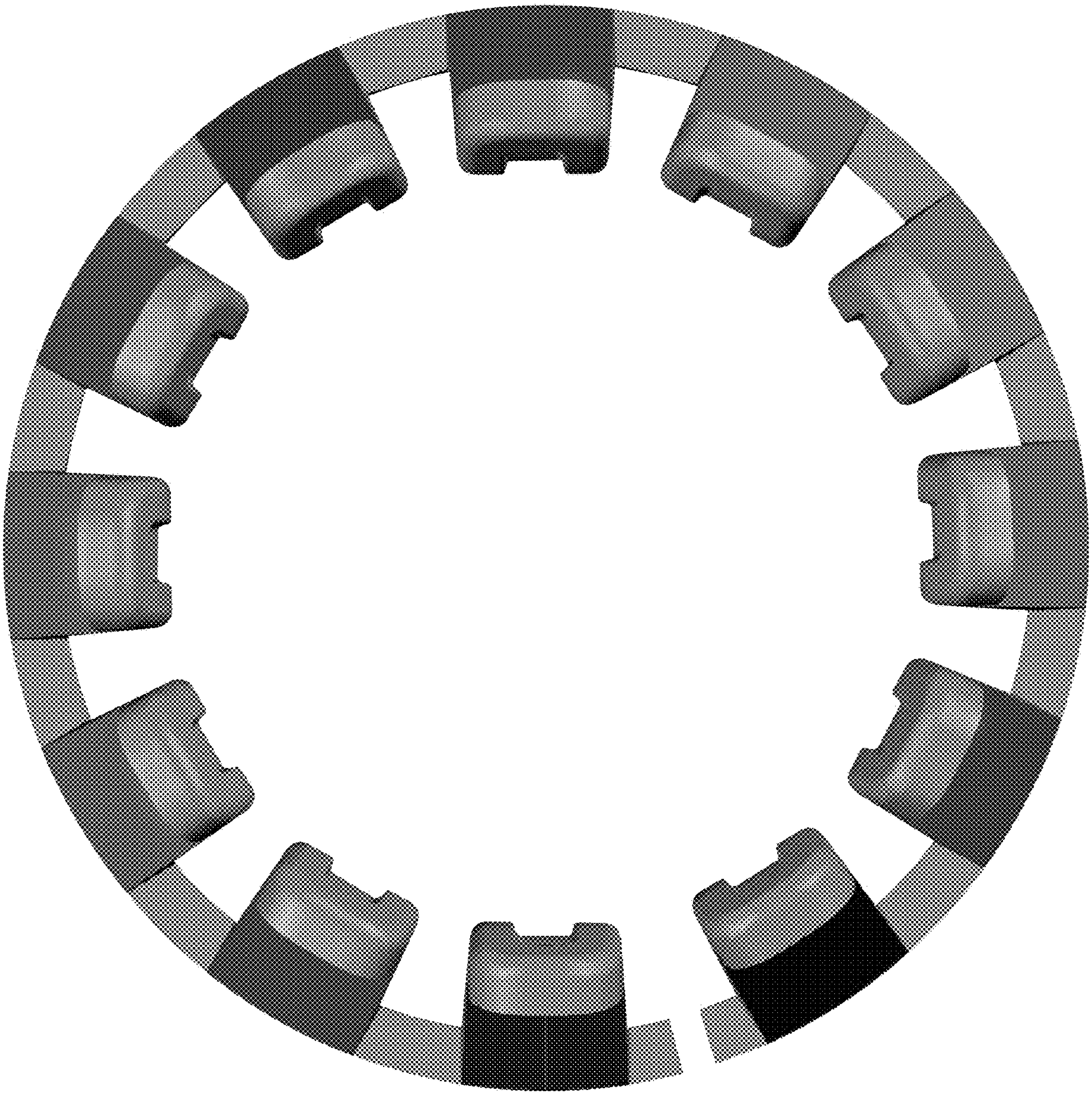

FIG. 6

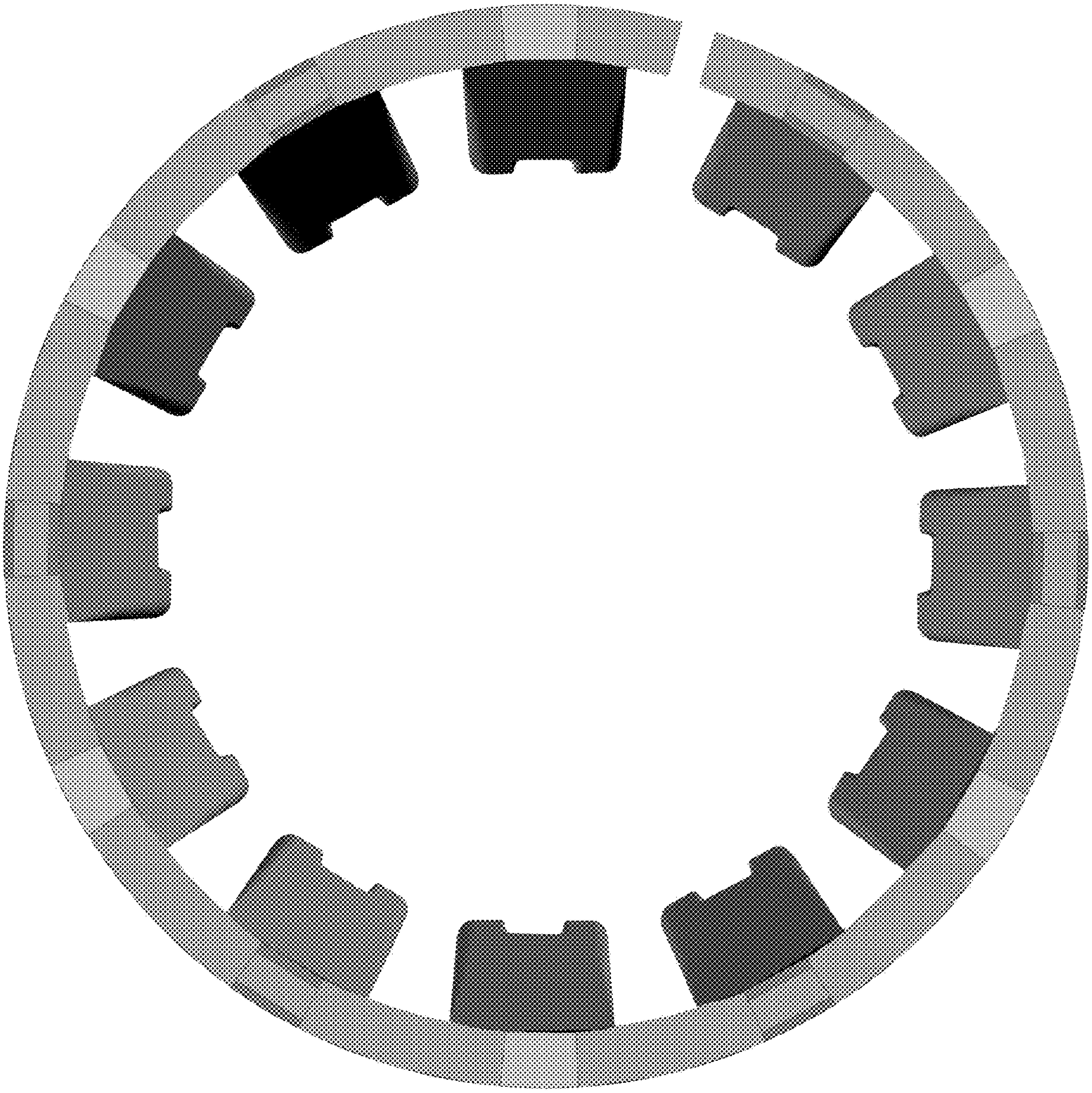

FIG. 7